



Koh Young to Unveil Next-Generation Inspection and Smart AI Solutions at NEPCON Asia 2026

Shenzhen, China – Koh Young Technology, the industry leader in True 3D measurement-based inspection solutions, will unveil its latest inspection platforms and AI-powered process solutions at NEPCON Asia 2026, October 27–29 at the Shenzhen World Exhibition & Convention Center in Shenzhen. Visitors to Booth 13E10 in Hall 13 will experience an extensive portfolio spanning solder paste inspection, automated optical inspection, dispensing process inspection, semiconductor inspection, and Smart AI Solutions.

The exhibit will demonstrate how Koh Young combines trusted measurement data with artificial intelligence and connected software to help manufacturers improve inspection performance, accelerate programming, optimize processes, and make more informed production decisions. The presentation reflects Koh Young's continued evolution from an inspection equipment company into an AI-powered solutions company guided by its identity, "Measure Everything, AI Everywhere."

New Nova Platforms Advance Inspection Performance

Two next-generation Nova platforms will be central to the exhibit. The new **KY8030 Nova** solder paste inspection system is engineered to deliver faster cycle times while maintaining the measurement accuracy and repeatability required for demanding, high-volume production environments.

Koh Young will also introduce the **Zenith Nova UHP**, an ultra-high-performance automated optical inspection platform designed around three critical capabilities: high speed, high resolution, and high-height inspection. This combination enables manufacturers to address increasingly demanding assemblies while balancing inspection performance, production throughput, and application flexibility.

Together, the Nova platforms demonstrate how Koh Young is advancing inspection performance across increasingly complex and demanding production environments.

Inspection for Challenging SMT Applications

The **Zenith UHS 9-way** AOI system will highlight Koh Young's advanced multi-view inspection capabilities. Its nine-way optical configuration provides comprehensive component and solder-joint visibility, while WFMI technology and support for components up to 60 millimeters high extend inspection capability across complex, densely populated, and high-profile assemblies.

For dispensing applications, the **Neptune C+** will demonstrate True 3D inspection of underfill and other transparent or translucent materials. By measuring the presence, position, coverage, and dimensional characteristics of dispensed material, Neptune C+ helps manufacturers identify process variation that can be difficult to evaluate with conventional two-dimensional imaging.

Advanced Semiconductor Inspection

Koh Young will also present specialized inspection technologies developed for semiconductor and advanced packaging processes. The **Meister S+** will focus on flux inspection, providing the measurement capability needed to evaluate challenging flux deposits before critical assembly operations.

The **Meister D+** will demonstrate advanced die inspection with an emphasis on detecting die cracks. As semiconductor packages become smaller, denser, and more complex, the ability to identify subtle defects and dimensional variation becomes increasingly important for protecting downstream yield and product reliability.



“Electronics manufacturers are being challenged to manage greater product complexity, tighter process windows, and higher production demands at the same time,” said Steven Choi, Managing Director of Koh Young China. “Our NEPCON Asia exhibit will show how accurate True 3D measurement, advanced inspection platforms, and AI-powered software can work together to turn production data into practical action. This connected approach helps manufacturers improve productivity today while preparing for the next generation of electronics and semiconductor manufacturing.”

From Inspection Data to Process Intelligence

Koh Young’s Smart AI Solutions will connect the hardware demonstrations and show how measurement data can create value across the production line.

- **KAP**, Koh Young’s AI-powered automatic programming solution, reduces the time and expertise required to create inspection programs. It uses artificial intelligence to automate major portions of the programming process, supporting faster new-product introduction and more consistent program creation.
- **Smart Review** applies AI-powered automatic judgment to improve defect classification and review consistency. Its feedback capabilities help reduce unnecessary operator intervention while creating a more efficient and standardized review process.
- **KPO Printer** and **KPO Mounter** use trusted inspection data to support process optimization at the solder paste printer and component mounter. These solutions extend inspection beyond defect detection by helping manufacturers address process variation closer to its source.
- **KSMART** transforms inspection results into Smart Factory Analytics, providing manufacturers with centralized visibility into production performance, yield, defects, and process trends. By converting large volumes of inspection data into actionable information, KSMART helps engineering teams identify variation, prioritize improvement opportunities, and make better production decisions.

The booth will demonstrate a connected manufacturing strategy where inspection systems generate reliable measurement data, AI accelerates decisions, and software translates those decisions into process improvements.

NEPCON Asia 2026 takes place October 27–29 at the Shenzhen World Exhibition & Convention Center in Bao’an, Shenzhen, China. Visit Koh Young in **Hall 13, Booth 13E10**. For exhibition details and visitor registration, visit [NEPCON Asia](https://www.nepconasia.com). Additional information about Koh Young’s participation is available at www.kohyoung.com.





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Koh Young Technology, Inc.

Koh Young helps manufacturers prevent defects, stabilize processes, and increase throughput. Since 2002, the company has led True3D™ measurement-based metrology and inspection, beginning with the industry's first 3D solder paste inspection system using patented dual-projection Moiré technology. Building on that foundation, Koh Young addresses complex applications including machined parts, press-fit and through-hole pins, conformal coatings, dispensed materials, and semiconductor packaging. A continuous innovation mindset and a customer-focused R&D approach underpin its leadership. With global operations and regional teams, Koh Young provides local support, training, and process expertise that turn inspection data into decisive, closed-loop action for a smarter factory. Learn more about our True 3D measurement-based inspection and smart factory solutions at www.kohyoung.com.